

EH-ES201

Low Energy SiP Module Data Sheet

12 Oct 2020 Version1.3



Professional **Bluetooth** Solution Provider

VERSION HISTORY

| Version | Comment |
|---------|--------------------------|
| V1.1 | First edition |
| V1.2 | Add antenna patterns |
| V1.3 | Updated pin descriptions |

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1. Introduction

EH-ES201 is a low-power Bluetooth® 5 module based on Nordic nRF52 series platform. With ultra-small size and powerful features. Powered by a highly efficient 64MHz 32-bit ARM® Cortex ™ M4 CPU and 192 KB Flash + 24 KB RAM.

EH-ES201 comes with a high-performance built-in antenna, which can connect up to 60m in an open environment. No external antenna is needed, and the ultra-small size of 7.0 * 7.0 * 1.4mm can reduce the PCB area requirements of customers' products and help customers realize ultra-small products. At the same time, the ES201 module can optionally support external antennas to meet customer requirements for antenna performance and layout in different occasions.

After purchasing EH-ES201, we will provide free technical support for the APP of the IOS system or the APP of the Android system.

2. Quick Specifications

| Bluetooth Version | | | | | |
|---------------------------|--|--|--|--|--|
| BLE version | Bluetooth 5 Low Energy | | | | |
| BLE Version | Bluetooth/SIG Mesh | | | | |
| Radio | | | | | |
| Frequency | 2402MHZ-2480MHZ | | | | |
| Transmit power | +4 to -20 dBm in 4 dB steps | | | | |
| Receiver sensitivity | -96dBm | | | | |
| Modulations | GFSK at 1 Mbps, 2 Mbps data rates | | | | |
| Antenna | Integrated (-1dBi peak); support onboard antenna or external | | | | |
| | antenna | | | | |
| ОТА | Supported | | | | |
| Electrical Specifications | | | | | |
| Power supply | 1.7V to 3.6V | | | | |
| Radio current consumption | 7.0 mA at +4 dBm TX power, | | | | |
| DC/DC at 3V | 4.6 mA at 0 dBm TX power, | | | | |
| | 4.6 mA in RX at 1 or 2 Mbps | | | | |
| | 0.3 μA in System OFF, no RAM retention | | | | |
| Radio current consumption | 0.5 μA in System OFF, full RAM retention | | | | |
| DC/DC at 3 V | 0.6 μA in System ON, no RAM retention | | | | |
| 35,25 4.5 1 | 0.8 μA in System ON, full RAM retention | | | | |
| | 1.5 μA in System ON, full RAM retention and RTC | | | | |
| Hardware | | | | | |
| Dimension | 7.0x7.0x1.4mm | | | | |
| Temperature Range | -30°C to +85°C | | | | |
| MCU | Highly efficient 64MHz 32-bit ARM® Cortex ™ M4 CPU | | | | |

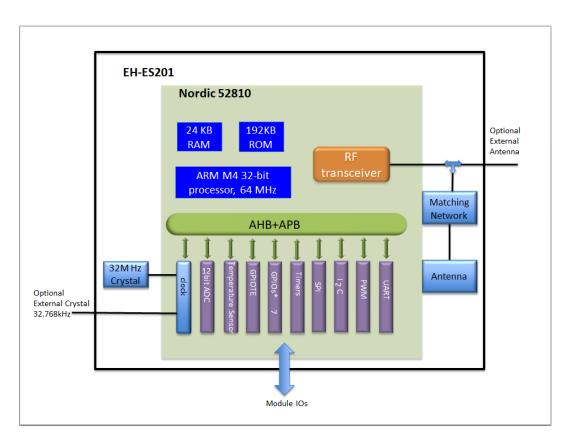
| Flash | 192 KB Flash | | | | |
|---|--------------------|-----|--------|------|--------|
| Ram | 24 KB | | | | |
| | Temperature sensor | I2C | GPIO*7 | UART | GPIOTE |
| Interfaces | SPI Master-slave | DWA | RTC | SWD | SPI |
| | interface | PWM | | | |
| Software | | | | | |
| Bluetooth mesh self-organizing network protocol | | | | | |
| Low power transmission protocol | | | | | |
| The Ehware's profile kit is used to develop the bluetooth 5.0 specification | | | | | |

3. Applications

- Smart buildings, Smart cities
- Industry 4.0
- Low-Power Sensor Networks
- Fitness / Sports / Health
- Smart Home
- Smart lighting systems

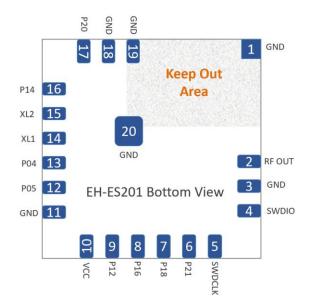
- iBeacons[™] / Proximity
- BLE Mesh applications
- Smart Toys / accessories
- Internet of Things
- Hotel Automation
- Office Automation

4. Block Diagram



5. Pin Descriptions

5.1 Pin-out





5.2 Pin Descriptions

| Pin | No. | Function | Remark |
|--------|-----|--------------------------|---------------------|
| RFOUT | 1 | Support external antenna | |
| GND | 2 | GND pin | Power GND |
| SWDIO | 3 | Support SWD | |
| SWDCLK | 4 | Support SWD | |
| P21 | 5 | Reset | Reset |
| P18 | 6 | General input/output | |
| P16 | 7 | General input/output | |
| P12 | 8 | General input/output | |
| VCC | 9 | 1.7-3.6V | Connect a capacitor |
| GND | 10 | GND pin | Power GND |
| P05 | 11 | General input/output | |
| P04 | 12 | General input/output | |
| XL1 | 13 | Connect external 32.768K | |
| | | crystal | |
| XL2 | 14 | Connect external 32.768K | |
| | | crystal | |

| P14 | 15 | General input/output | |
|-----|----|----------------------|--|
| P20 | 16 | General input/output | |
| GND | 17 | Power GND | |
| GND | 18 | Power GND | |
| GND | 19 | Power GND | |
| GND | 20 | Power GND | |

Note:

- 1 MP test points should be reserved, including UART TX, UART RX, RESET.
- 2 For debugging, it is recommended to keep the SWDIO and SWDCLK test points.
- 3 If used with MCU chip, it is recommended to connect the reset pin.

6. Electrical Specifications

6.1 7.1 Recommended Operation Conditions

| Operating Condition | Min | Typical | Max | Unit |
|------------------------------|------|---------|---------|------|
| Operating Temperature Range | -30 | +25 | +85 | °C |
| Storage Temperature Range | -40 | +25 | +85 | °C |
| Working Voltage | 1.7 | +3.0 | 3.6 | V |
| Voltage for module | 1.8 | - | 3.6 | V |
| I/O Supply Voltage (VDD_PIO) | -0.4 | +3.0 | +3.6 | V |
| AIO input | 0 | - | VDD_BAT | V |
| Frequency range | 2400 | - | 2500 | MHz |

Note: Terminal voltages other than RF

6.2 Module power consumption

| Power mode | Current Consumption(Max) |
|---------------------------------------|---|
| Transmission mode (3V DC/DC) | 7.0 mA, Active TX mode(TX power:4dBm) |
| Transmission mode (3V DC/DC) | 4.6 mA, Active TX mode(TX power:0dBm) |
| | 4.6 mA , Active RX mode(1M ot 2M) |
| | 0.3 μA in System OFF, no RAM retention |
| Standby mode | 0.5 μA in System OFF, full RAM retention |
| (3V DC/DC) | 0.6 μA in System ON, no RAM retention |
| | 0.8 μA in System ON, full RAM retention |
| System current consumption (3V DC/DC) | 1.5 μA in System ON, full RAM retention and RTC |

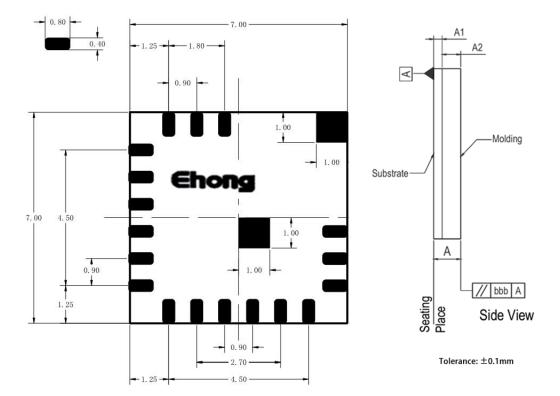
• minimum power consumption: Condition: VBAT=3V, VDDIO=3V, ambient temperature:25 °C.

7. Software/ Firmware

| Software Support | |
|-------------------|--|
| Standard Software | Ehong provide module with standard software for customer to develop. |
| | Support to make some modification and support customized MAC address |
| SDK development | Ehong provide SDK and description |

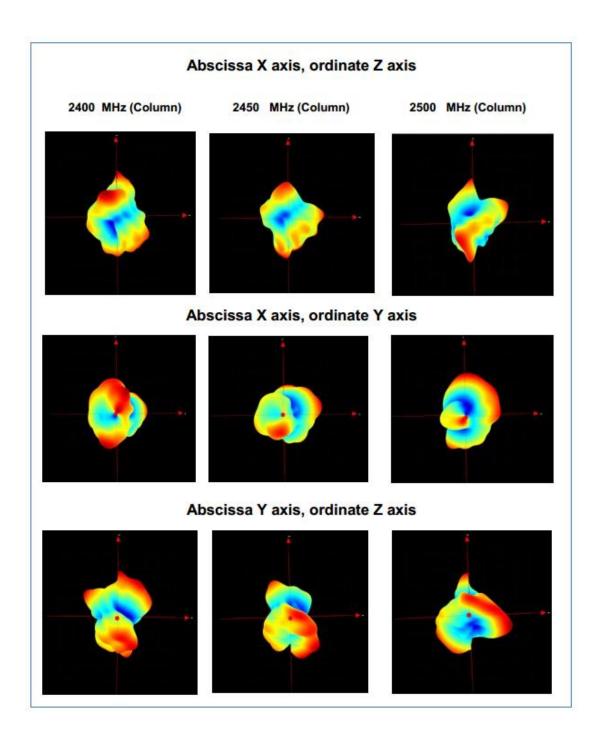
8. Mechanical Data

8.1 Dimensions and recommend PCB



9. Antenna Patterns

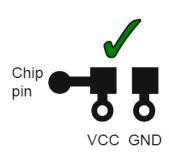
Antenna patterns are based on the EH-ES201 Evaluation Kit



10. Layout suggestion

10.1 Power supply precautions

- Module power: 3v button battery or DC 3.3v
- Connect the power pin capacitors as close as possible to the chip and pins
- · Use capacitors to decouple power from the chip
- · Use capacitors to prevent noise from coupling back into the power plane



Note: When supplying power to the module, it is necessary to use a small ripple (generally, the power ripple within 30mV is sufficient). It is recommended to use the LDO to power the module when selecting the power supply. The LDO PCB layout needs to be away from some inductive sensor, DC -DC power supply \ inductance, etc., in the PCB design, it is necessary to have a reliable grounding process, and it must not exceed the maximum voltage used by the module to prevent the module from irrecoverable damage.

10.2 Layout Guidelines

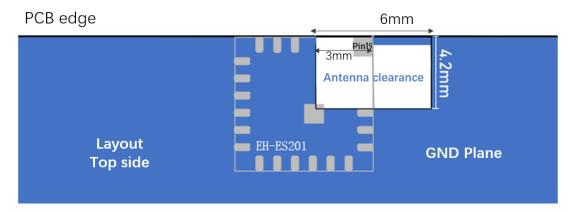
For ES201, the integrated antenna needs a proper ground plane to radiate efficiently.

The area protruding from under the antenna section of the module should be free of copper and other metals.

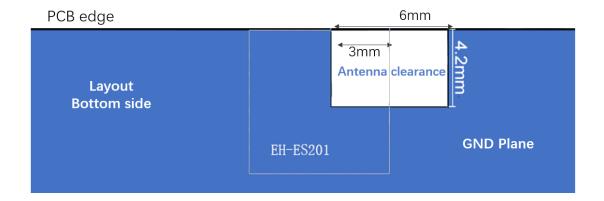
The module should be placed on the edge of the PCB with the antenna edge facing outward.

The antenna needs to be processed for clearance during layout, and requires a sufficient clearance area. (When designing, pay attention to both the top and bottom layers. If conditions allow, it is recommended to hollow out the clearance directly when designing the PCB board. No form of electrical operation is allowed in the projection area of the antenna to ensure the radiation effect of the antenna.

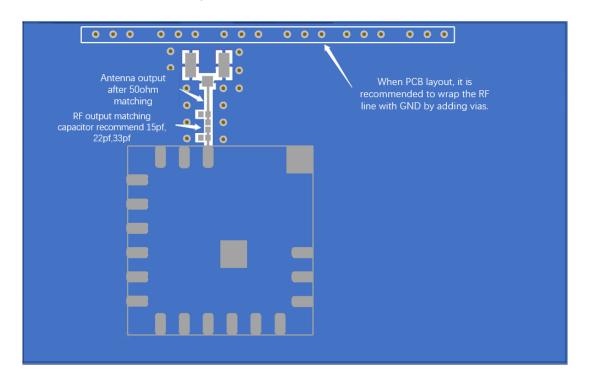
When using IPEX technology (external antenna) by yourself, please pay attention to 50 Ohm matching in the RF output part, and in the RF output part, it is recommended to use vias and ground to cover the PCB layout to prevent RF on the PCB There is unnecessary loss during the transmission process, and the radio frequency part needs to be kept at a distance of more than 10mm from some interference source parts. Generally, it is necessary to avoid any electrical components during the layout.



Note: Pin19 Need to be grounded.



10.3 EH-ES201 PCB layout



11. Development Kit

EH-ES201-EVK is designed based on EH-ES201 module.

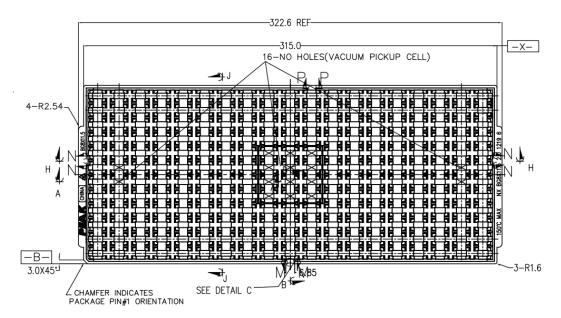
The development kit integrates LED, reset button, IO interface, SWD. There are 7 IO ports. It also has a rich interface and completeness to help customers easily complete product development and testing.



12. Packaging and Labeling

Each reel or tray will be placed in an antistatic bag with a desiccant bag and a humidity card, and in a 36x25x12cm box. Antistatic warnings and labels are attached to the outside of the packaging.

12.1 Tray package



12.2 Packing Label



13. Related Documents

Ehong Documents:

Visit website and download:

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Sales: <u>sales@ehonglink.com</u>